

Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**
 Contact Info: ti.com/support
 Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**
 Created on: **06/04/2022**

Details for "OPA2810IDT"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
OPA2810IDT	NIPDAU	Level-2-260C-1 YEAR	TI MALAYSIA A/T	D 8	4.9x3.9x1.75	88

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.057592	97.587095	975871	0.065409	654
Not Categorized	Proprietary Materials		0.000006	0.010167	102	0.000007	0
Precious Metals	Palladium	7440-05-3	0.001416	2.399349	23993	0.001608	16
Precious Metals	Silver	7440-22-4	0.000002	0.003389	34	0.000002	0
Sub-Total			0.059016	100	1000000	0.067026	670
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.25508	80	800000	0.289701	2897
Thermoplastics	Epoxy	85954-11-6	0.06377	20	200000	0.072425	724
Sub-Total			0.31885	100	1000000	0.362126	3621
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	24.8676	97.52	975200	28.242761	282428
Copper and Its Alloys	Iron	7439-89-6	0.5865	2.3	23000	0.666103	6661
Copper and Its Alloys	Phosphorus	7723-14-0	0.00765	0.03	300	0.008688	87
Zinc and Its Alloys	Zinc	7440-66-6	0.03825	0.15	1500	0.043441	434
Sub-Total			25.5	100	1000000	28.960994	289610
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.989248	95.12	951200	1.123514	11235
Precious Metals	Gold	7440-57-5	0.008112	0.78	7800	0.009213	92
Precious Metals	Palladium	7440-05-3	0.04264	4.1	41000	0.048427	484
Sub-Total			1.04	100	1000000	1.181154	11812
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	52.877481	88.000001	880000	60.054291	600543
Other Plastics and Rubber	Carbon Black	1333-86-4	0.180264	0.3	3000	0.20473	2047
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.330484	0.55	5500	0.375339	3753
Thermoplastics	Epoxy	85954-11-6	6.699817	11.15	111500	7.609151	76092
Sub-Total			60.088046	100	1000000	68.243511	682435
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	1.043552	100	1000000	1.185188	11852
Sub-Total			1.043552	100	1000000	1.185188	11852
Total			88.049464			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

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[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.